

High-performance polishing slurry for SiC wafers

NANOBITM

Application

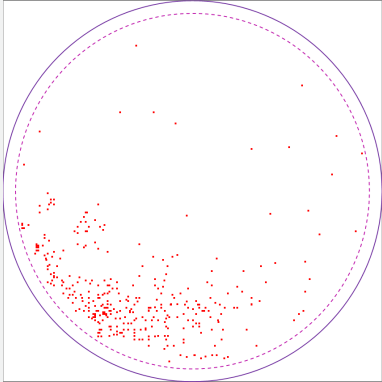
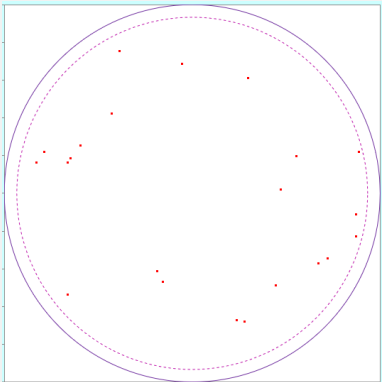
- Polishing slurry mixed of two-components for SiC wafers.

Summary

- MnO₂ abrasives provide high-speed, low damage processing in a single step.
- Possible by suppressing the rate difference between the C-face and the Si-face.
- Easy cleaning for polisher and wafer.
- Can be used in a recycling way.



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	Commercially available epi-ready wafer	After polishing with NANOBI TM
Mapping of sub surface damage detected		
Density of sub surface damage	158(/cm ²)	10(/cm ²)

※ Evaluation using a mirror electron microscope(Mirelis VM1000 by Hitachi High-Tech Co.)



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